

MICROELECTRONIC DEVICE ASSEMBLIES INCLUDING
ASSEMBLIES WITH RECURVED LEADFRAMES, AND
ASSOCIATED METHODS

ABSTRACT OF THE DISCLOSURE

Microelectronic device assemblies, including assemblies with recurved leadframes, and associated methods are disclosed. An assembly in accordance with one embodiment includes a microelectronic device having a first surface, a second surface facing opposite from the first surface, and a plurality of bond sites accessible from the first surface. An operable microelectronic feature can be located between the first and second surfaces. The assembly can further include a leadframe positioned proximate to the microelectronic device, with the leadframe having a plurality of conductive leadfingers, each being electrically coupled to a corresponding bond site of the microelectronic device, and extending around the microelectronic device to face toward the second surface. This arrangement can be used to support single microelectronic devices, and/or stacked microelectronic devices.

Figure: 1